

## **Breakthrough Ultra Thin Wafer Support Solution Ready for the Semiconductor Market**

*AMS brings innovative technology to leading chip manufacturers.*

Portland, OR (PRWeb) July 8, 2005--Advance Material Sciences, Inc. (AMS) will introduce a major advance in wafer thinning technology at SEMICON West in San Francisco, CA July 12-14. Even before its official launch, the AMS ultra thin wafer support solution has begun to attract considerable attention from leading players in the international semiconductor device industry. Early adopters are currently being trained and qualified in the new process.

The core of the breakthrough solution is AMS's patent pending Protective Disc System (PDS™), which enables the high-volume, cost-effective production of ultra-thin silicon and compound semiconductor wafers. The PDS™ process, an innovation of AMS's world-class team of engineers, permits the high-volume manufacture (HVM) of ultra-thin wafers below 75 microns, while improving yields and reducing costs. This new wafer substrate and process virtually eliminates the breakage that often results from the use of conventional handling tools by increasing the rigidity of ultra-thin wafers beyond that of current taping technology. The innovation makes possible ultra-thin wafers that are surprisingly strong and durable.

The PDS™ solution also results in dramatically lower costs to manufacturers through increased yields for both wafers and devices. The PDS™ solution integrates seamlessly into the semiconductor back-end process and is fully compatible with existing grinding and stress relief technology

Michael Lubitz, Chairman of AMS, said, "We are pleased to be able to offer this exciting new technology for wafer manufacturing and processing to the industry. Our customers will now have access to technology that enables them to become leaders in high-volume wafer thinning. We currently have several customers who are qualifying the PDS™ solution for ultra-thin silicon and compound wafers."

AMS will be exhibiting with its OEM partner, PCT Systems, in the South Hall, booth 538.

Please contact Kim Bell, Vice President of Sales for more information: email protected from spam bots

### About Advanced Material Sciences

AMS has developed a cost-effective wafer support substrate solution enabling high volume wafer thinning below 75 microns. The PDS™ imparts sufficient strength and rigidity to the wafer, enabling the wafer to be safely processed and handled thus, increasing wafer and device yields while reducing total cost of ownership. The PDS™ solution easily integrates into the semiconductor back-end process and is compatible with existing grinding and stress relief technologies. AMS leads the industry in the development of advanced, high-volume manufacturing, wafer-thinning process technology. For more information, please visit the Company's website at [www.advmatsci.com](http://www.advmatsci.com). For investor-specific information, please visit [www.intellectcap.com](http://www.intellectcap.com)

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